

NOTES:

1. MATERIAL:
 - 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP.,UL94V-0.
 - 1.2 TERMINAL: COPPER ALLOY.
 - 1.3 FITTING NAIL: COPPER ALLOY.
2. FINISH:
 - 2.1 CONTACT:
 - 50u" MIN. NICKEL UNDERPLATING OVERALL.
 - 1u" MIN GOLD PLATING ON CONTACT AREA.
 - 2.2 SOLDER:
 - 50u" MIN. NICKEL UNDER PLATING OVER ALL
 - 1u" MIN GOLD PLATING ON SOLDER AREA.
3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
4. SPEC.PLS REFER TO PS-53019-XXXXX-XXX
5. PACKAGE PLS REFER TO 53019-XXXXX-03-TRP (WITH COVER) OR 53019-XXXXX-TRP(WITHOUT COVER)
6. PART NUMBER

53019-XXX X X-XXX

NO OF CKT
007:7PIN

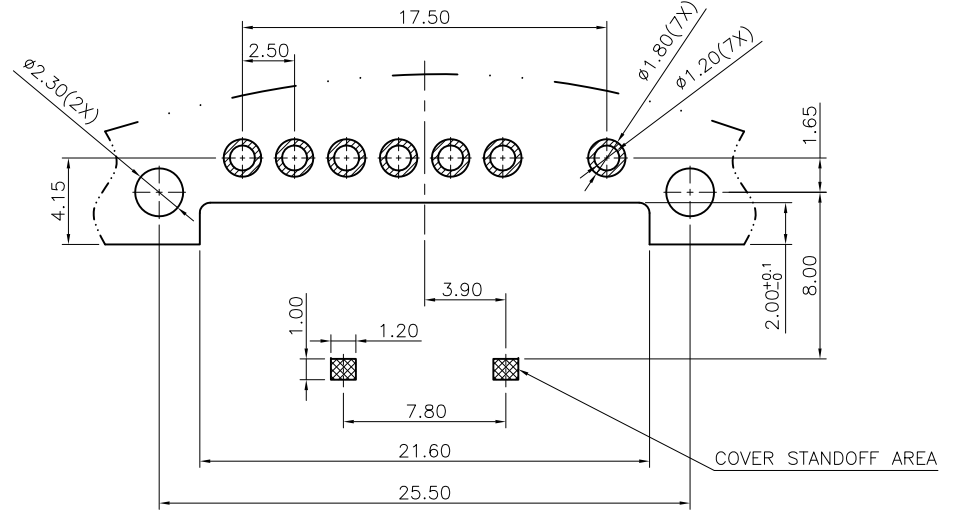
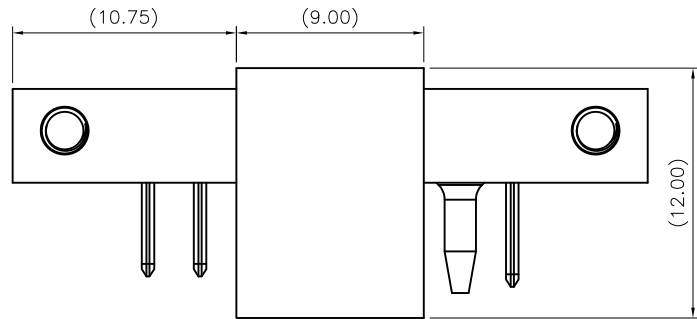
PACKING

- 0:TAPE & REEL
- 1:TUBE
- 7:TAPE & REEL WITH COVER
- 8:TUBE WITH COVER

XXX	COLOR	MATERIAL	HF
001	BLACK	HF PLASTIC	Y

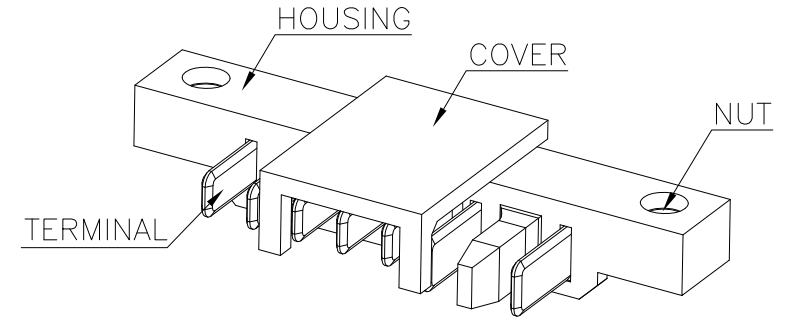
PLATING
1: GOLD FLASH

一般公差 TOLERANCES X ±0.50 XX ±0.15 X ±0.25 .XXX ±0.10 ANGLES ±2°		宏致電子股份有限公司 Aces Electronic Co.,Ltd.	
檢驗尺寸標示 SYMBOLS INDICATE CLASSIFICATION DIMENSION	品名 (TITLE) 2.5mm BATTERY CONN T/H TYPE	製圖 (DR) 12/06/13 Huanty	審核 (CHKD) TONY
MARK IS CRITICAL DIM. MARK IS MAJOR DIM.	圖號 (DWG.NO) 53019-XXXXX-XXX	核准 (APPD) JASON	
表面處理 (FINISH)	比例 (SCALE) 單位 (UNITS) 3:1 mm		張數 (SHEET) 1 OF 2 尺寸 (SIZE) A4 版數 (REV) 0

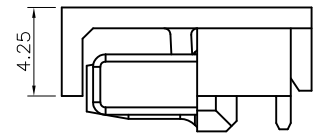
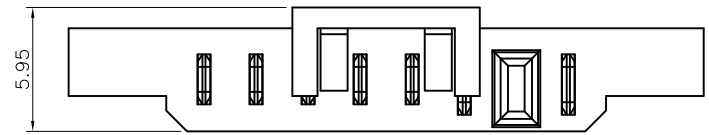


RECOMMEND PCB LAYOUT
TOLERANCE±0.05mm

COVER STANDOFF AREA



WITH COVER



WITH COVER

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